DSC612NI3A-010T



Two-Output Low Power MEMS Clock Generator

General Description

The DSC612NI3A-010T is a two-output low power MEMS clock generator.

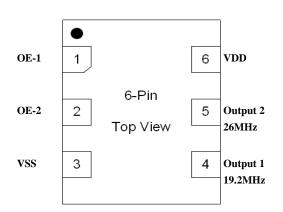
The MEMS based clock generator eliminates the need of external crystal or reference clock.

Refer to DSC612 master data sheet to read full descriptions.

Features

- Two LVCMOS clock outputs: 19.2MHz, 26MHz
- Ultra-small package size: 2.0mm x 1.6mm 6L LGA
- High stability: ±20ppm
- Temperature range: -40°C to +85°C
- Low power consumption: ~5mA (both outputs active)
- Wide supply voltage range: 1.71V -3.63V VDD
- Excellent shock and vibration immunity
- High reliability
- Lead free and RoHS compliant
- AEC-Q100 automotive grade available

Pin Configuration and Description



6-pin 2.0mm x 1.6mm 6L LGA

Pin Number	Pin Name	Pin Type	Pin Description		
1	OE-1	I	Output Enable H = Output Active L = Output Disabled (High Impedance)		
2	OE-2	I	Output Enable H = Output Active L = Output Disabled (High Impedance)		
3	VSS	Power	Power Supply Ground		
4	Output 1	О	19.2MHz LVCMOS Clock Output Controlled by Pin 1 (OE-1)		
5	Output 2	О	26MHz LVCMOS Clock Output Controlled by Pin 2 (OE-2)		
6	VDD	Power	Power Supply		

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Ordering Information

Ordering Part Number	Temperature Range	High Stability	Shipping	Package
DSC612NI3A-010T	-40°C to +85°C	±20ppm	Bag	2.0mm x 1.6mm 6L LGA
DSC612NI3A-010TT	-40°C to +85°C	±20ppm	Tape and Reel	2.0mm x 1.6mm 6L LGA

Devices are Green and RoHS compliant. Sample material may have only a partial top mark.

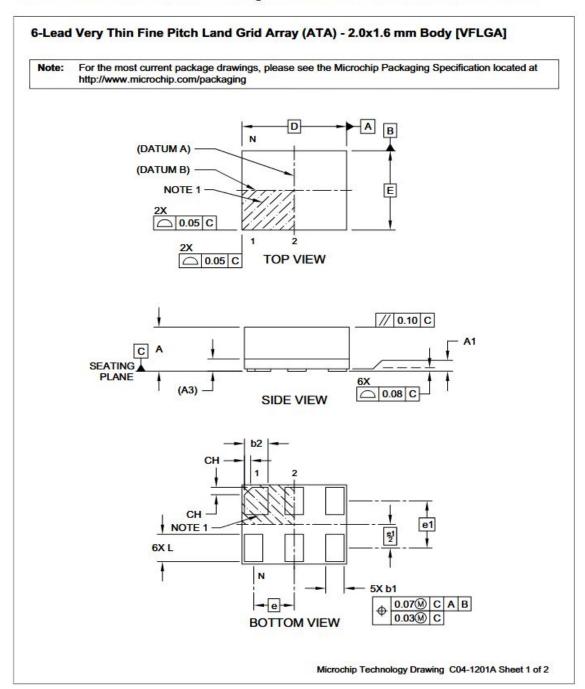
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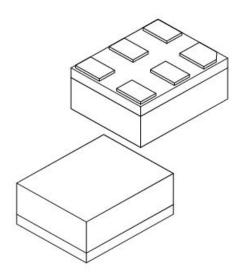
6-Lead 2.0 mm x 1.6 mm VFLGA Package Outline and Recommended Land Pattern

Microchip Technology Inc.



6-Lead Very Thin Fine Pitch Land Grid Array (ATA) - 2.0x1.6 mm Body [VFLGA]

For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS			
Dimension	MIN	NOM	MAX		
Number of Terminals	N	6			
Terminal Pitch	е	0.775 BSC			
Terminal Pitch	e1	0.95 BSC			
Overall Height	Α	0.79	0.84	0.89	
Standoff	A1	0.00	0.02	0.05	
Substrate Thickness (with Terminals)	A3	0.20 REF			
Overall Length	D	2.00 BSC			
Overall Width	E	1.60 BSC			
Terminal Width	b1	0.30	0.35	0.40	
Terminal Width	b2	0.40	0.45	0.50	
Terminal Length	L	0.50	0.55	0.60	
Terminal 1 Index Chamfer	СН	-	0.15	-	

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package is saw singulated
- 3. Dimensioning and tolerancing per ASME Y14.5M

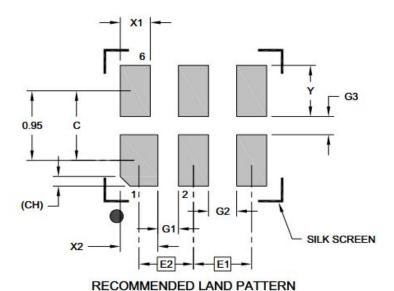
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1201A Sheet 2 of 2

6-Lead Very Thin Fine Pitch Land Grid Array (ATA) - 2.0x1.6 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units MILLIMETERS Dimension Limits NOM MAX Contact Pitch 0.78 BSC E1 0.73 BSC Contact Pitch E2 Contact Spacing С 0.95 Contact Width (X4) 0.40 X1 Contact Width (X2) X2 0.45 Contact Pad Length (X6) Y 0.70 Space Between Contacts (X4) G1 0.28 G2 0.38 Space Between Contacts (X3) Space Between Contacts (X3) G3 0.25

CH

Notes:

Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Contact 1 Index Chamfer

Microchip Technology Drawing C04-3201A

0.13 X 45° REF